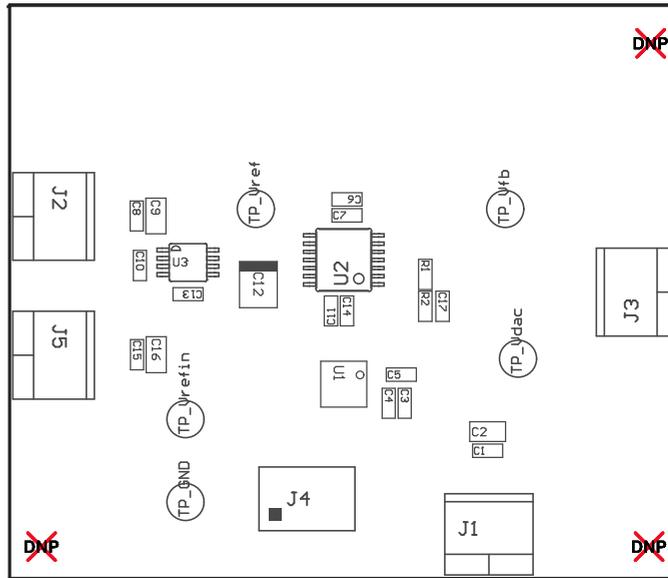
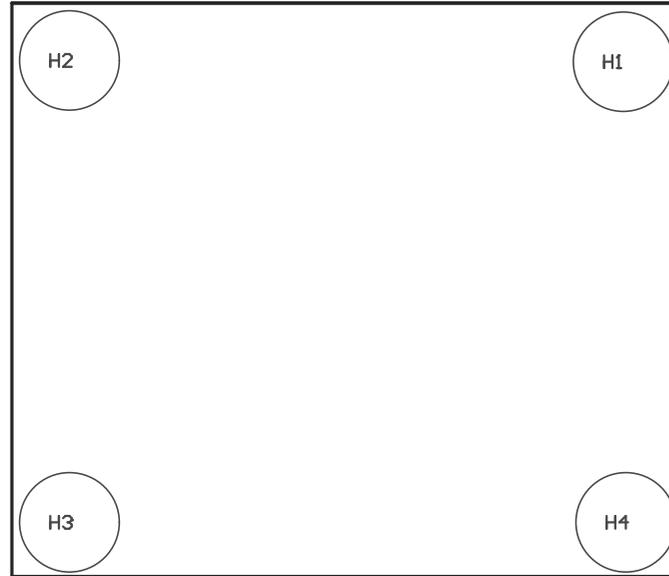


- Z21 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
- Z22 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- Z23 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIPD192	REV: E3	SUN REV: Not In VersionControl
	TID #: TIPD192		
PLOT NAME = TopAssembly Drawing	GENERATED : 11/1/2016 2:30:18 PM		TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIPD192	REV: E3	SUN REV: Not In VersionControl
	TID #: TIPD192		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 11/1/2016 2:30:18 PM		TEXAS INSTRUMENTS

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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